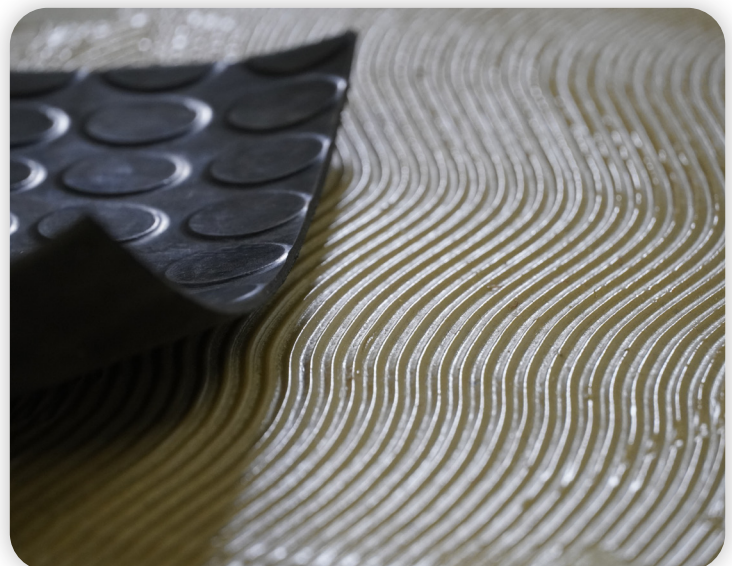
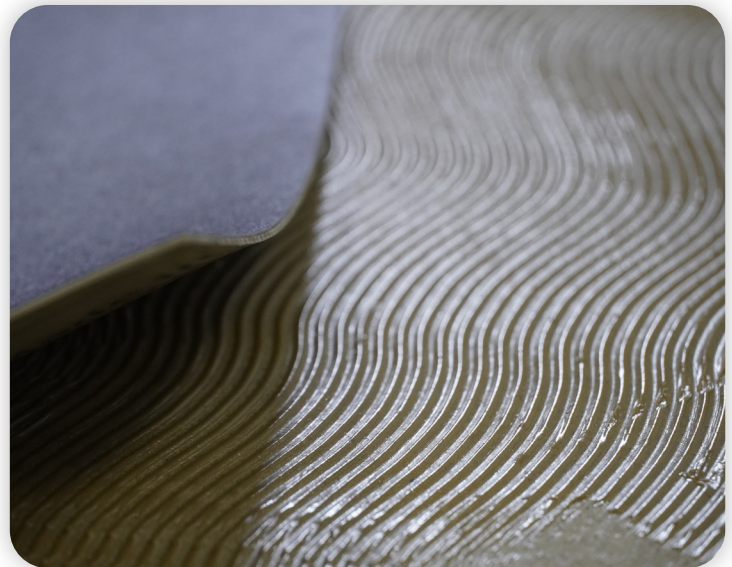







# Lechner

SOLUTIONS FOR PROFESSIONAL CONSTRUCTION



## FIELDS OF APPLICATION

-  RESILIENT LINE
-  WOOD LINE
-  MARINE LINE
-  ARTIFICIAL GRASS LINE
-  EQUIPMENT AND ACCESSORIES LINE

# GOMMAPOL CONDUTTIVO

TWO-COMPONENT ADHESIVE FOR INSTALLING RESILIENT CONDUCTIVE FLOORING

## DESCRIPTION AND USES PRODUCT FOR PROFESSIONAL USE ONLY

Two-component, high-performance, conductive epoxy-polyurethane adhesive, suitable for gluing conductive rubber flooring, PVC and linoleum on absorbent and non-absorbent substrates.

### PRODUCT FEATURES



#### Application

Lechner toothed trowel no.1-2-4



#### Suitable for conductive flooring



#### Suitable for indoor use



#### Suitable for under-floor heating systems



#### Suitable for wheelchairs



#### Catalysis ratio

9.4:0.6 (A:B)

#### Waiting time

10 minutes

#### Dry-to-walk-on time

12-24 hours

#### Final setting time

72 hours



#### Pot life

90 minutes



#### Storage

12 months in original sealed packaging



#### Consumption

350-500 g/m<sup>2</sup>



#### Chemical base

Component A epoxy-polyurethane resin with conductive pigments. Component B mix of amines.



#### Operating temperature

+10 - +30 °C



#### Cleaning

Solvent CH 500 (as long as the product is fresh)

### METHOD OF USE

The substrate must be compact, in good condition, clean, established, permanently dry and free from detaching substances such as oils, waxes, excess dust, etc. If there are any cracks or fissures, these must be first repaired with SIGEPOX. Maximum allowable moisture content:

- Cementitious substrates: max. 2.0%; with underfloor heating 1.7%.

- Gypsum or anhydrite substrates: max. 0.5%; with underfloor heating 0.2%.

It is recommended to check that there is no rising damp. Any excessively dusty or insufficiently compact surfaces should be treated in advance using appropriate primers, such as polyurethane primers (PU series) or EPOPRIMER. The surface of stone and non-absorbent surfaces such as ceramics should be treated with warm water and caustic soda, and then rinsed thoroughly. It is recommended to apply PROMOX on the cleaned and dried surface to improve adhesion. Substrates with an insufficiently flat laying surface can be leveled with cement-based leveling compounds, such as LIVELLANTE 140M, ULTRADUR, RASODUR, RASODUR MAXI, LEVELFAST or LEVELFAST S. Non-heating substrates with excessive humidity (max. 5%) must be first waterproofed with appropriate primers such as: PU series, EPOPRIMER or TRIX, depending on the absorbency of the surface. Heating substrates can be reinforced but not waterproofed (contact the Technical Department for more information). Anhydrite screeds should be sanded, dusted and primed according to the manufacturer's instructions. Lay the flooring to be fixed in the desired rooms on the substrate before installation. Equipotential bonding (grounding) must be carried out, following the various methods prescribed by current Standards (CEI, DIN, etc.). The conductive grid made of copper strips (thickness 0.08- 0.1 mm, width 10-25 mm) can be fixed to the substrate using GOMMAPOL CONDUTTIVO, spread with a thin-toothed trowel (type LECHNER no. 1); thoroughly mix the two components in their respective catalysis ratio of 9.4: 0.6 using a mechanical stirrer to create a paste that is homogeneous in color and appearance. Apply the adhesive on the substrate using an appropriately sized notched trowel, incorporating any residual surface dust. After waiting for the partial evaporation of the VOC contained in the adhesive (about 10 mins), the flooring should be laid on top of the glue, pressing it and massaging it immediately afterwards from the center outwards to promote adhesion and to release any air bubbles. Repeat after about 2-3 hours. Rigid, warped or uneven flooring must be held pressed to the substrate using appropriate weights until the adhesive has completely set. To seal the joints in the flooring, especially for outdoor installation, it is recommended to make the glue overflow laterally from the joints to allow the flooring sheets to be fixed together, cleaning the excess adhesive immediately afterwards using SOLVENTE CH 500. Wait for the product to set, approximately 12 hours, before walking on the flooring.

### OTHER INFORMATION

Various kinds of rubber, PVC and resilient materials are commercially available; it is therefore recommended to test the adhesive on the material in the event of uncertainty. Some rubbers may contain separating agents or paraffins; they should therefore be cleaned with SOLVENTE CH 500 or be sanded before installation. The application and gluing times indicated in the product features correspond to an ambient temperature of +20°C and a relative air humidity of 50%. The product should be stored at the same temperature as the desired room. For outdoor installation during hot weather, the flooring should be laid at the coolest time of the day to avoid the formation of bubbles in the case of porous substrates such as cement.

### INSTRUCTIONS

**FOR SAFETY AND DISPOSAL:** Consult the relevant safety data sheet before using the product. Gloves are recommended during use. Ventilate the room during and after use. Follow all applicable safety regulations. Do not dispose of any residue in the ground, waterways or drains. To dispose of the product and other waste deriving from the activity, adhere closely to the provisions of Legislative Decree no. 152/2006 and subsequent amendments and additions of the Consolidated Environmental Act (Testo Unico Ambientale). For further information, please contact our Technical Assistance Department. The content of this sheet integrates and replaces the previous version, rendering it null and void.

**WARNINGS:** The data provided in this data sheet reflects our best theoretical and practical knowledge. However, it is not possible for us to consider every detail, therefore this information should not be considered as binding. In the event of any doubt, please contact our technical offices.